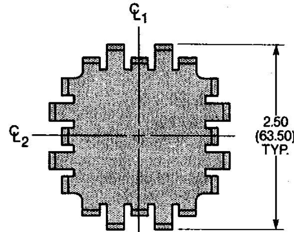
CTS®

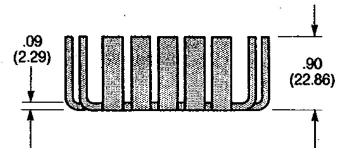
Series HP1

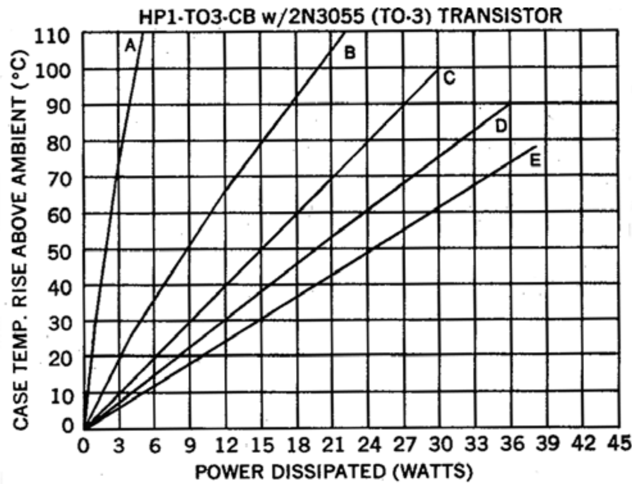
Technical Data

METAL CASE, CASE-MOUNTED SEMICONDUCTORS

HP1 Series for Single TO-3 or Stud Mount Devices







DESCRIPTION OF CURVES

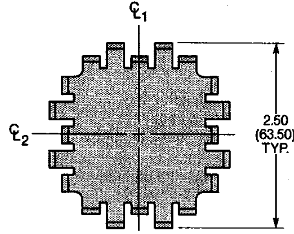
A. N.C. Horiz. Device Only Mounted to G-10.
A. N.C. Horiz. & Vert. With Dissipator.
B. 200 RPM w/Diss.
C. 500 RPM w/Diss.
E. 1000 RPM w/Diss.

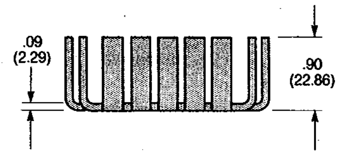
- Thermal Resistance Case to Sink is 0.1-0.3 °C/W w/Joint Compound.
- Derate 1.0 °C/watt for unplated part in natural convection only.

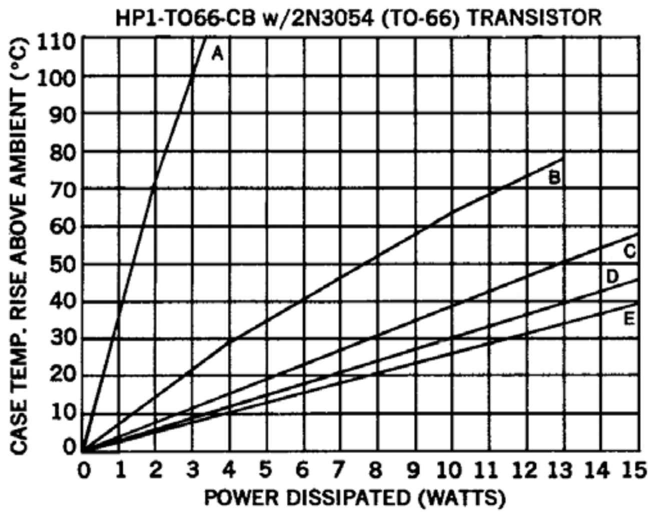
Ordering Information

IERC PART NO.			Semiconductor Accommodated	Hole patt. Ref. No. (see pg. 1-28)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP1-000-U	HP1-000-CB	HP1-000-B	Undrilled	--	35.0
HP1-TO3-U	HP1-TO3-CB	HP1-TO3-B	TO-3	16	35.0
HP1-TO3-33U	HP1-TO3-33CB	HP1-TO3-33B	TO-3 IC	17	35.0
HP1-TO3-44U	HP1-TO3-44CB	HP1-TO3-44B	TO-3 panel mount	31	35.0
HP1-436-U	HP1-436-CB	HP1-436-B	TO-3 (4-pin)	18	35.0
HP1-TO6-U	HP1-T06-CB	HP1-T06-B	TO-6, TO-36	19	35.0
HP1-TO15-U	HP1-TO15-CB	HP1-TO15-B	TO-15, DO-5	23	35.0
HP1-420-U	HP1-420-CB	HP1-420-B	Universal	27	35.0

HP1 Series for Single TO-66 Outline







DESCRIPTION OF CURVES

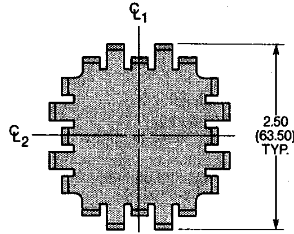
B. N.C. Horiz. Device Only Mounted to G-10.
D. N.C. Horiz. & Vert. With Dissipator.
E. 200 RPM w/Diss.
F. 500 RPM w/Diss.
E. 1000 RPM w/Diss.

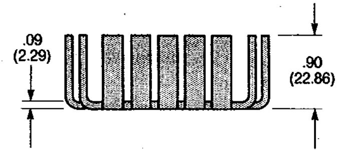
- Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 1.0 °C/watt for unplated part in natural convection only.

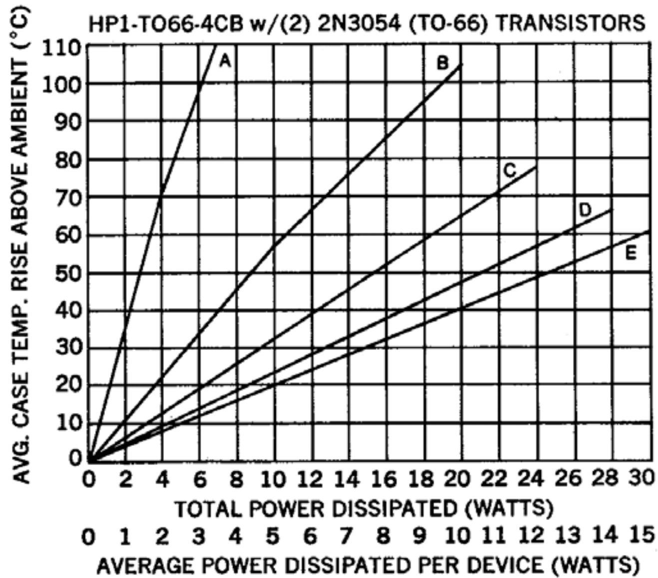
Ordering Information

IERC PART NO.			Semiconductor Accommodated	Hole patt. Ref. No. (see pg. 1-28)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP1-TO66-U	HP1-TO66-CB	HP1-TO66-B	TO-66	24	35.0
HP1-TO66-35U	HP1-TO66-35CB	HP1-TO66-35B	TO-66 IC	25	35.0
HP1-TO66-49U	HP1-TO66-49CB	HP1-TO66-49B	TO-66 IC (Socket)	26	35.0

HP1 Series for Dual TO-66 Outline







DESCRIPTION OF CURVES

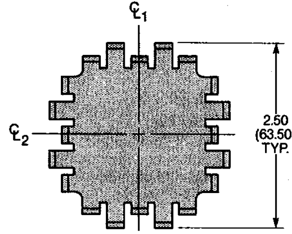
C. N.C. Horiz. Device Only Mounted to G-10.
G. N.C. Horiz. & Vert. With Dissipator.
H. 200 RPM w/Diss.
I. 500 RPM w/Diss.
E. 1000 RPM w/Diss.

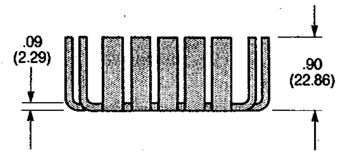
- Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 2.0 °C/watt per device for unplated part in natural convection only.
- Case Temperatures Match Within 2°C at equivalent power levels.

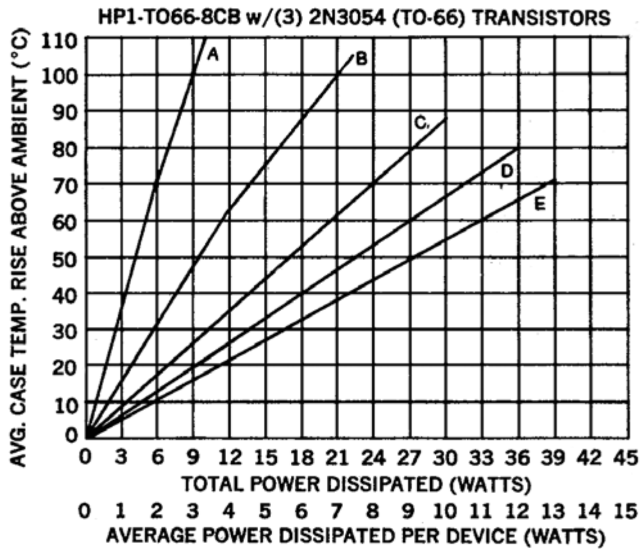
Ordering Information

IERC PART NO.			Semiconductor Accommodated	Hole patt. Ref. No. (see pg. 1-30)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP1-TO66-4U	HP1-TO66-4CB	HP1-TO66-4B	Two TO-66s	32	35.0
HP1-TO66-36U	HP1-TO66-36CB	HP1-TO66-36B	Two TO-66 Ics	34	35.0

HP1 Series for Three TO-66 Outline







DESCRIPTION OF CURVES

D. N.C. Horiz. Device Only Mounted to G-10.
J. N.C. Horiz. & Vert. With Dissipator.
K. 200 RPM w/Diss.
L. 500 RPM w/Diss.
E. 1000 RPM w/Diss.

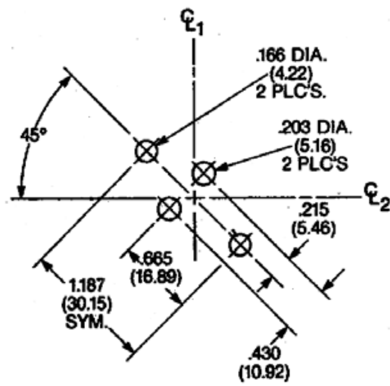
- Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 3.0 °C/watt per device for unplated part in natural convection only.
- Case Temperatures Match Within 2°C at equivalent power levels in natural convection.

Ordering Information

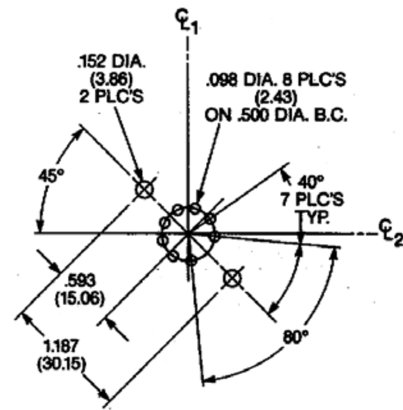
IERC PART NO.			Semiconductor Accommodated	Hole patt. Ref. No. (see pg. 1-30)	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
HP1-TO66-8U	HP1-TO66-8CB	HP1-TO66-8B	Two TO-66s	33	35.0
HP1-TO66-39U	HP1-TO66-39CB	HP1-TO66-39B	Two TO-66 Ics	35	35.0

HOLE PATTERNS

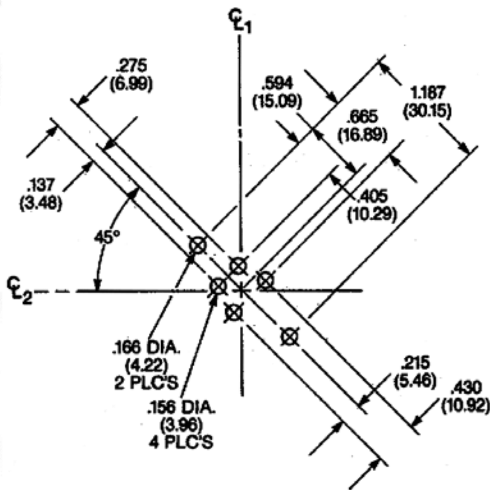
16. Hole pattern no. 1 accommodates T0-3s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



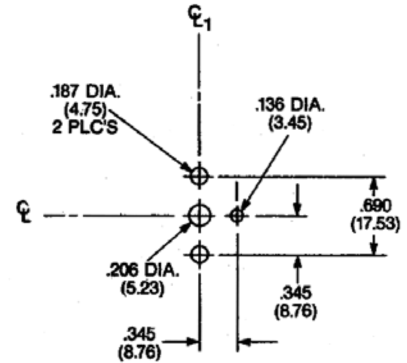
17. Hole pattern no. 202 accommodates T0-3 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



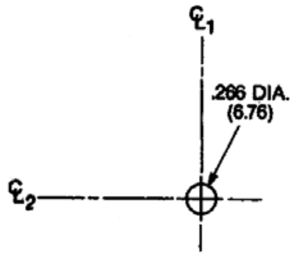
18. Hole pattern no. 436 accommodates t0-3s (4-pin). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



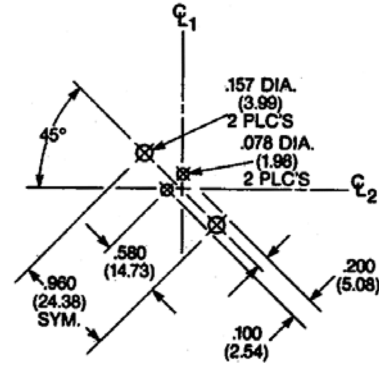
19. Hole pattern no. 2 accommodates T0-6s or T0-36s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



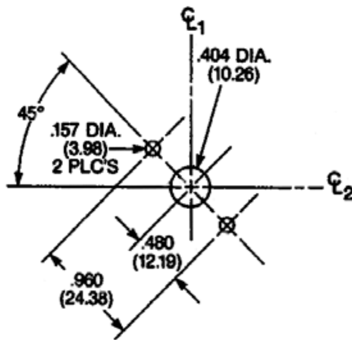
23. Hole pattern no. 3 accommodates TO-15s, DO-5s and other ¼" stud mount devices. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



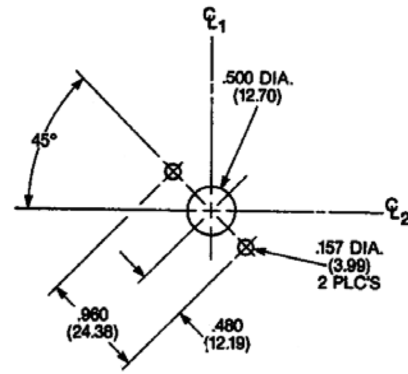
24. Hole pattern no. 114 accommodates TO-66s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



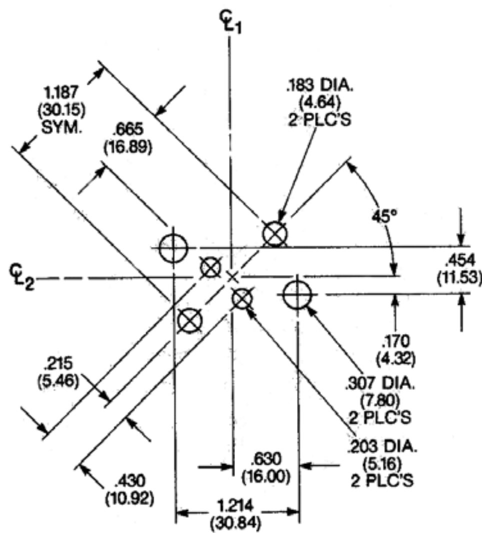
25. Hole pattern no. 199 accommodates TO-66 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



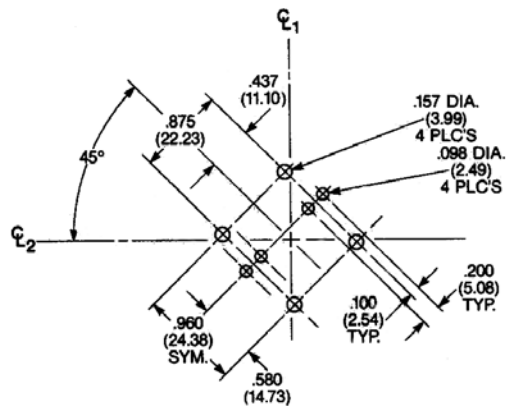
26. Hole pattern no. 226 accommodates TO-66 ICs (socket). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



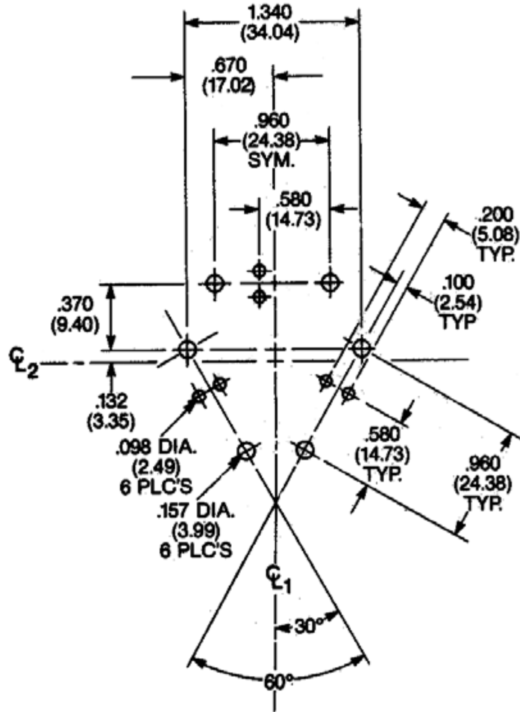
31. Hole pattern no. 213 accommodates one TO-3 (panel mounted). Available in HP1 and HP3 series heat dissipators only.



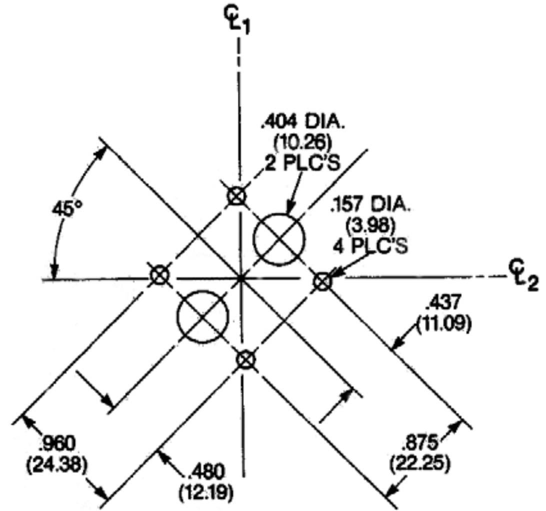
32. Hole pattern no. 150 accommodates two TO-66s. Available in HP1 and HP3 series heat dissipators only.



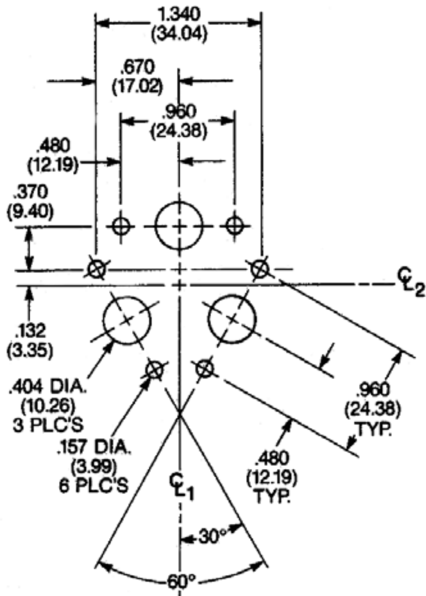
33. Hole pattern no. 185 accommodates three TO-66s. Available in HP1 and HP3 series heat dissipators only.



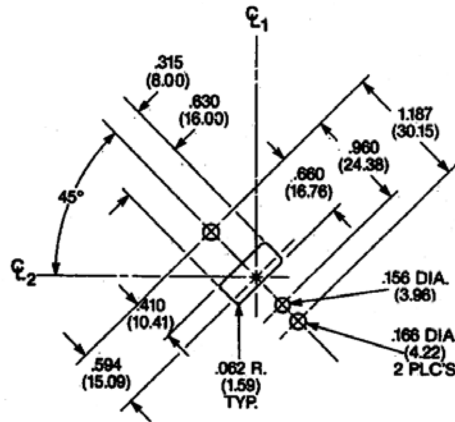
34. Hole pattern no. 201 accommodates two TO-66s ICs. Available in HP1 and HP3 series heat dissipators only.



35. Hole pattern no. 203 accommodates three TO-66 ICs. Available in HP1 and HP3 series heat dissipators only.



27. Hole pattern no. 420 (Universal) accommodates T0-3s, T0-66s, T0-126s, T0-127s, or T0-220s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



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